SHEET 1 OF 1

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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

INFORMATION DISCLOSURE CITATION IN AN APPLICATION  PROPERTY OF TRACES  (PTO-1449)					ATTY. DOCKET NO. <b>57454-963</b>	RIAL NO. <b>/633,576</b>				
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1 Applicant's unique citation designation number (optional). 2 Applicant is to place a check mark here if English language Translation is attached.